



# CSP/MICRO BGA Test & Burn-In Socket For Devices Up to 55mm Sq.

## FEATURES:

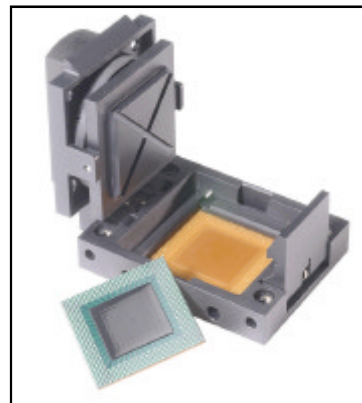
- For Test & Burn-In of CSP, MicroBGA, DSP, LGA, SRAM, DRAM and Flash Devices.
- Any device on 0.50mm pitch or larger.
- 4 Point crown insures "scrub" on solder oxides.
- Single Point Probes available for small land area contact pads.
- Signal path during test only .077" (1.92mm)
- Socket is easily mounted and removed to & from the BIB due to solderless pressure mount compression spring probes which, are accurately located by two molded plastic alignment pins and mounted with four stainless steel screws.
- The gold over nickel plated compression spring probes leave very small witness marks on the bottom surface of the device solderballs.
- Standard molded socket format can accommodate any device package of 55mm<sup>2</sup> or smaller.
- The spring loaded, cam actuated Pressure Pad applies proper force against the device after the lid is closed, latched and the cam is rotated to it's detented location. Reversing the cam removes the force applied to the device prior to unlatching the spring loaded lid to it's upright position.

## GENERAL SPECIFICATIONS:

- Molded socket components are UL94V-0 PEEK and/or Ultem.
- 1dB Bandwidth at 1Ghz (0.80mm pitch) (large probe).
- Estimated Contact Life: =500,000 cycles.
- Compression spring probes are heat treated Beryllium Copper Alloy with 30u" min. [.75um] Gold per Mil-G-45204 over 30u" min.[.75um] Nickel per QQ-N-290.
- Contact Force = 9-12g per contact on 0.50 - 0.75mm pitch  
17-20g per contact on 0.80mm pitch or larger.
- Operating Temperature = -55°C (min.) to 150°C (max.); -67°F (min.) to 302°F (max.).
- All Hardware is Stainless Steel.
- Typical Burn-in Temperature = 125°C.

## MOUNTING CONSIDERATIONS:

- See "PCB FOOTPRINT TOP VIEW" for requirements.
- Sockets must be handled with care when mounting or removing sockets to/from PCB.
- Test board PCB diameter = .026" (0.66mm) (large probe)  
= .016" (0.40mm) (small probe)



*Note: Aries specializes in custom design and production. In addition to the standard products shown on this page, special materials, platings, sizes, and configurations can be furnished, depending on quantities. Aries reserves the right to change product specifications without notice.*

## ORDERING INFORMATION

CONSULT FACTORY

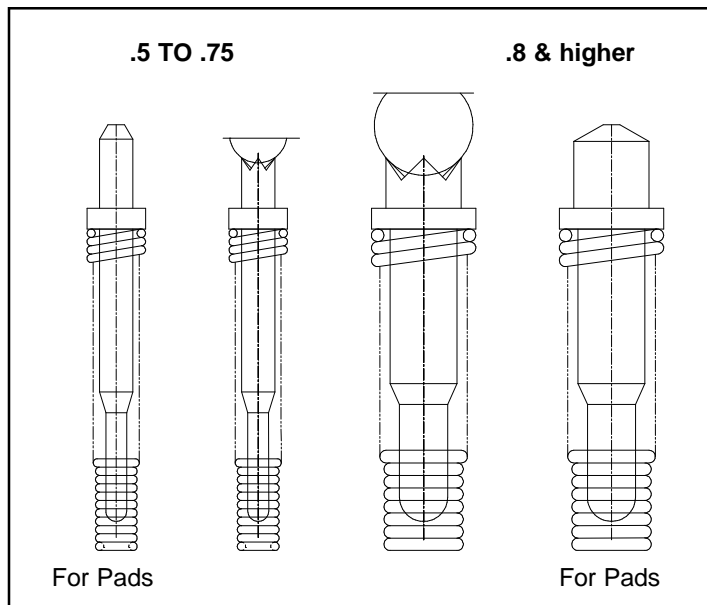
**PATENT PENDING**

**SEE CSP DATASHEETS:  
23017 FOR UP TO 13MM  
23018 FOR UP TO 27MM  
23019 FOR UP TO 40MM**

**ALL DIMENSIONS: INCHES [MILLIMETERS]**

All tolerances ± .005 [.13] unless otherwise specified

SPRING PROBES



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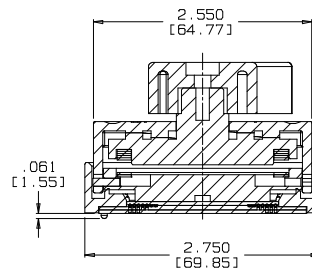
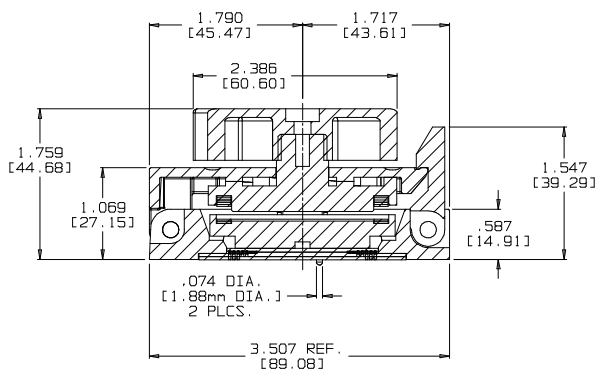
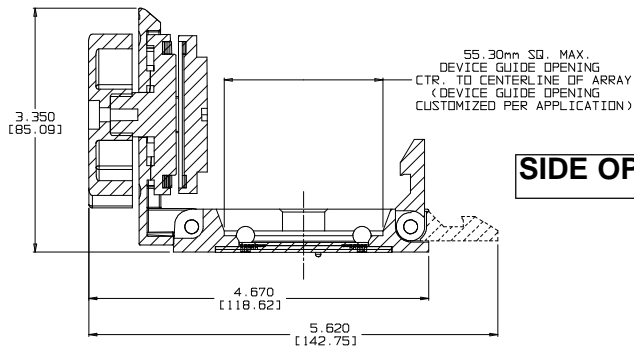
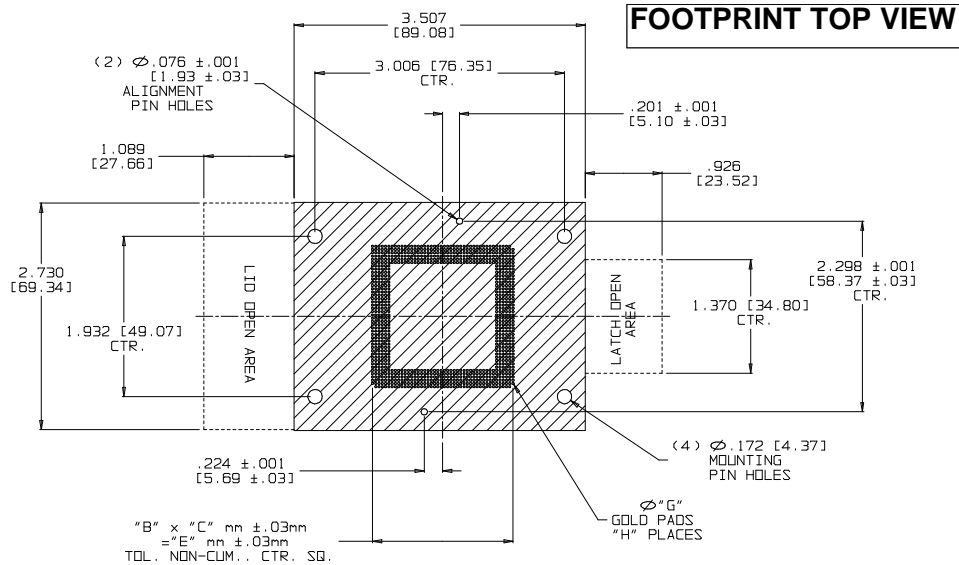


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Rev. B  
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